



Click [here](#) for the 3D model.

Dimensions

Chip Size	1808
L	4.572mm +/-0.381mm (0.18 in +/-0.015 in)
W	2.032mm +/-0.381mm (0.08 in +/-0.015 in)
T	1.651mm MAX (0.065 in MAX)

Packaging Specifications

Packaging	Waffle
Packaging Quantity	25000

General Information

Series	SMD Mil PRF123
Style	SMD Chip
Description	SMD Chip, Ultra Stable
RoHS	No
Prop 65	⚠ WARNING: Cancer and reproductive harm - http://www.p65warnings.ca.gov .
SCIP Number	8780dfd-a0b3-4664-b80c-18c07cfab0d1
Termination	Tin
Failure Rate	N/A
AEC-Q200	No
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	470 pF
Capacitance Tolerance	5%
Voltage DC	50 VDC
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	BP
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1MHz 1.0Vms
Dissipation Factor	2.5%
Insulation Resistance	100 GOhms

单击下面可查看定价，库存，交付和生命周期等信息

[>>KEMET\(基美\)](#)